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August 2014

FQPF5P20

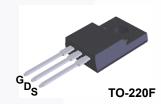
P-Channel QFET[®] MOSFET -200 V, -3.4 A, 1.4 Ω

Description

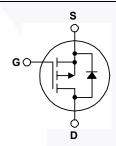
This P-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, DC motor control, and variable switching power applications.

Features

- -3.4 A, -200 V, $R_{DS(on)}$ = 1.4 Ω (Max.) @ V_{GS} = -10 V, I_D = -1.7 A
- Low Gate Charge (Typ. 10 nC)
- Low C_{rss} (Typ. 12 pF)
- · 100% Avalanche Tested







Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQPF5P20 FQPF5P20RDTU	Unit	
V_{DSS}	Drain-Source Voltage		-200	V	
I _D	Drain Current - Continuous (T _C = 25°C)		-3.4	Α	
	- Continuous (T _C = 100°C)		-2.15	Α	
I _{DM}	Drain Current - Pulsed	(Note 1)	-13.6	Α	
V _{GSS}	Gate-Source Voltage		± 30	V	
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	330	mJ	
I _{AR}	Avalanche Current	(Note 1)	-3.4	Α	
E _{AR}	Repetitive Avalanche Energy	(Note 1)	3.8	mJ	
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	-5.5	V/ns	
P _D	Power Dissipation (T _C = 25°C)		38	W	
	- Derate Above 25°C		0.3	W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C	
T _L	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds.		300	°C	

Thermal Characteristics

Symbol	Parameter	FQPF5P20 FQPF5P20RDTU	Unit	
$R_{\theta JC}$	ermal Resistance, Junction-to-Case, Max. 3.29		°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	C/VV	

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQPF5P20	FQPF5P20	TO-220F	Tube	N/A	N/A	50 units
FQPF5P20RDTU	FQPF5P20	TO-220F (LG-formed)	Tube	N/A	N/A	50 units

Elerical Characteristics $T_C = 25$ °C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-200			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = -250 μA, Referenced to 25°C		-0.17		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -200 V, V _{GS} = 0 V	-		-1	μΑ
		V _{DS} = -160 V, T _C = 125°C			-10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = -30 V, V _{DS} = 0 V			-100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = 30 V, V _{DS} = 0 V			100	nA
On Cha	aracteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	-3.0		-5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = -10 V, I _D = -1.7 A		1.1	1.4	Ω
g _{FS}	Forward Transconductance	V _{DS} = -40 V, I _D = -1.7 A		2.15		S
	ic Characteristics		T			
C _{iss}	Input Capacitance	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V},$		330	430	pF
C _{oss}	Output Capacitance	f = 1.0 MHz		75	98	pF
C _{rss}	Reverse Transfer Capacitance			12	15	pF
Switch	ing Characteristics					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = -100 \text{ V}, I_{D} = -4.8 \text{ A},$ $R_{G} = 25 \Omega$		9	28	ns
t _r	Turn-On Rise Time			70	150	ns
t _{d(off)}	Turn-Off Delay Time	5 32		12	35	ns
t _f	Turn-Off Fall Time	(Note 4)		25	60	ns
Qg	T O O!	\\ - 400\\ I - 40 A		10	13	
∽g	Total Gate Charge	$V_{DS} = -100 \text{ V}, I_{D} = -4.8 \text{ A},$		_		nC
Q _{gs}	Gate-Source Charge	$V_{DS} = -160 \text{ V}, I_{D} = -4.8 \text{ A},$ $V_{GS} = -10 \text{ V}$		2.8		nC nC

Drain-Source Diode Characteristics and Maximum Ratings

		•				
I _S	Maximum Continuous Drain-Source Diode Forward Current				-3.4	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		-		-13.6	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = -3.4 A			-5.0	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V, I}_{S} = -4.8 \text{ A,}$	-	175		ns
Q _{rr}	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$	-	1.07		μС

- **Notes:**1. Repetitive rating : pulse-width limited by maximum junction temperature. 2. L = 42.8 mH, I_{AS} = -3.4 A, V_{DD} = -50 V, R_G = 25 Ω , starting T_J = 25°C. 3. $I_{SD} \le$ -4.8 A, di/dt \le 300 A/µs, $V_{DD} \le$ BV $_{DSS}$, starting T_J = 25°C. 4. Essentially independent of operating temperature.

Typical Characteristics

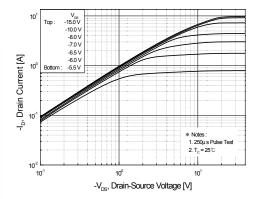


Figure 1. On-Region Characteristics

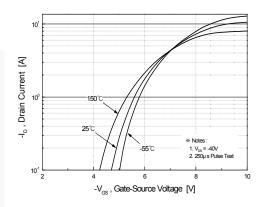


Figure 2. Transfer Characteristics

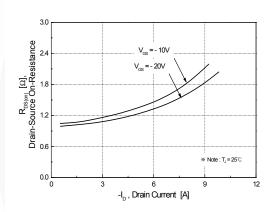


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

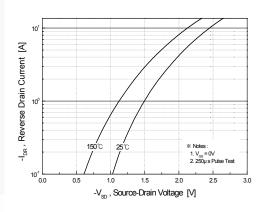


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

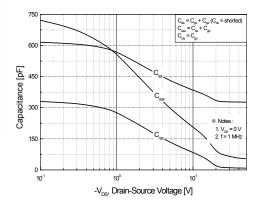


Figure 5. Capacitance Characteristics

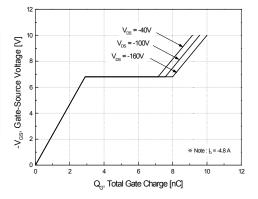
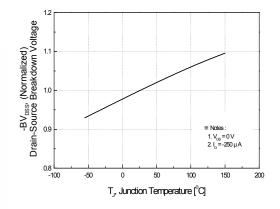


Figure 6. Gate Charge Characteristics

Typical Characteristics (Continued)



R_{DS(ON)}, (Normalized) Drain-Source On-Resistance 1.0 0.0 L -100 150 200

Figure 7. Breakdown Voltage Variation vs. Temperature

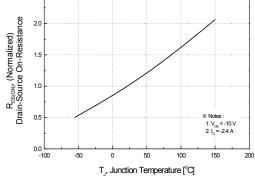
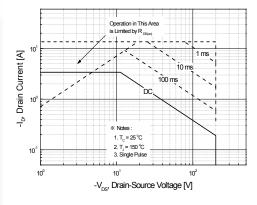


Figure 8. On-Resistance Variation vs. Temperature



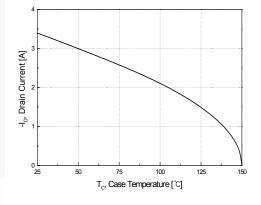


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

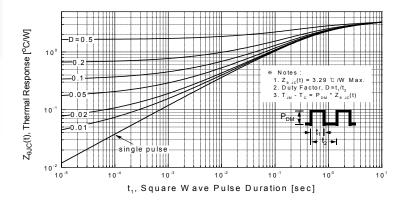


Figure 11. Transient Thermal Response Curve

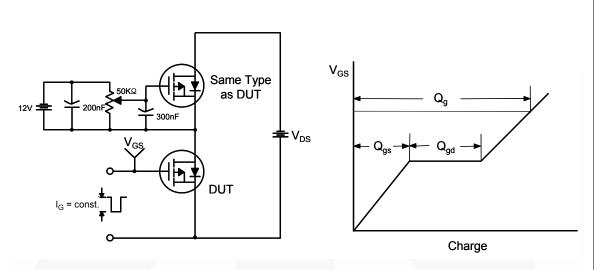


Figure 12. Gate Charge Test Circuit & Waveform

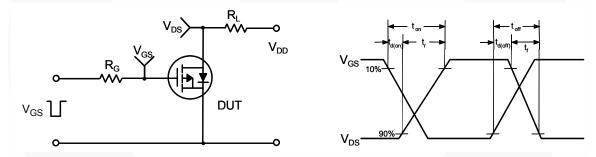


Figure 13. Resistive Switching Test Circuit & Waveforms

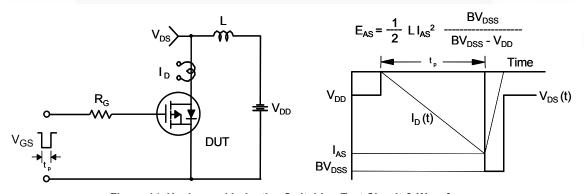
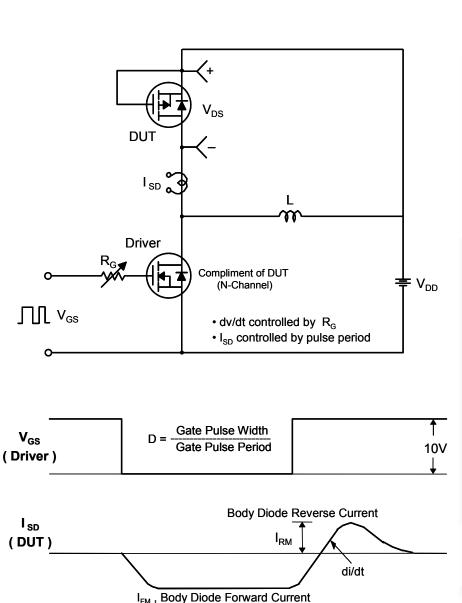


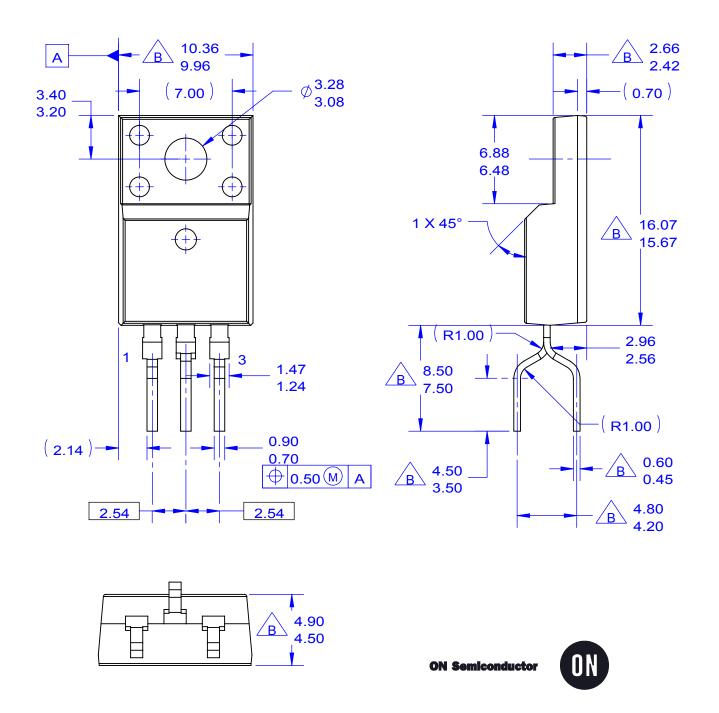
Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



V_{DS}
(DUT)

Body Diode
Forward Voltage Drop
Body Diode Recovery dv/dt

Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

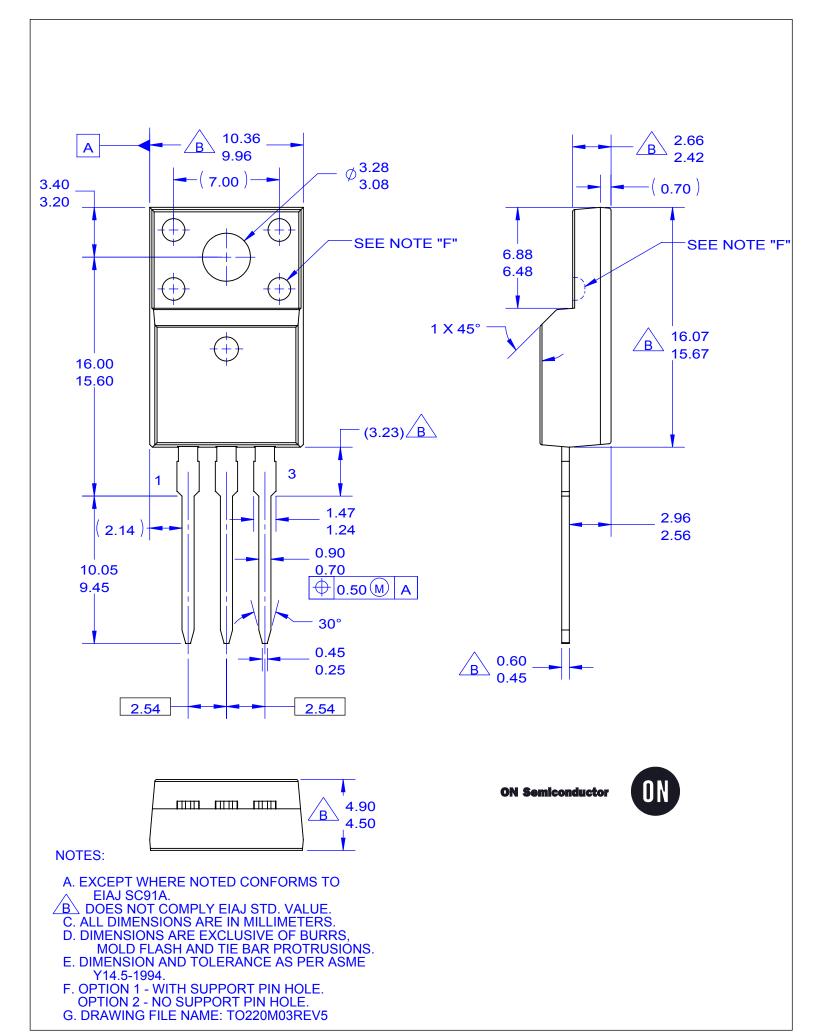


NOTES:

- A. EXCEPT WHERE NOTED CONFORMS TO EIAJ SC91A.

 B DOES NOT COMPLY EIAJ STD. VALUE.
 C. ALL DIMENSIONS ARE IN MILLIMETERS.

- D. DIMENSIONS ARE EXCLUSIVE OF BURRS MOLD FLASH AND TIE BAR PROTRUSIÓNS.
- E. DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994.
- F. DRAWING FILE NAME: TO220N03REV2



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